65536-word × 16-bit High Speed CMOS Static RAM

HITACHI

ADE-203-415A (Z) Rev. 1.0 Dec. 25, 1996

Description

The HM62W1664HB is an asynchronous high speed static RAM organized as 64-kword \times 16-bit. It realize high speed access time (25/30 ns) with employing 0.8 μ m CMOS process and high speed circuit designing technology. It is most appropriate for the application which requires high speed, high density memory and wide bit width configuration, such as cache and buffer memory in system. The HM62W1664HB is packaged in 400-mil 44-pin SOJ for high density surface mounting.

Features

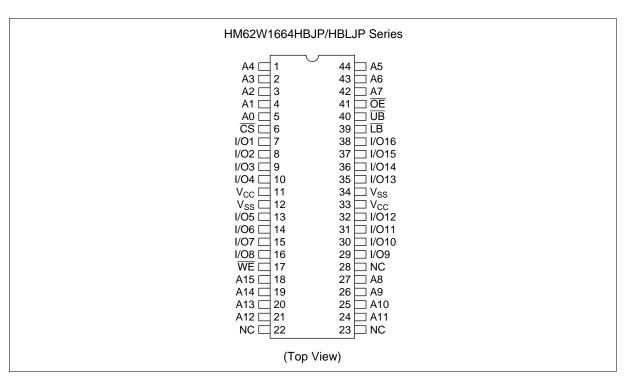
- Single 3.3 V supply $(3.3 \text{ V} \pm 0.3 \text{V})$
- Access time: 25/30 ns (max)
- Completely static memory
 - No clock or timing strobe required
- Equal access and cycle times
- Directly LV-TTL compatible
 - All inputs and outputs
- 400-mil 44-pin SOJ package
- Center V_{CC} and V_{SS} type pinout

Ordering Information

Type No.	Access time	Package
HM62W1664HBJP-25 HM62W1664HBJP-30	25 ns 30 ns	400-mil 44-pin plastic SOJ (CP-44D)
HM62W1664HBLJP-25 HM62W1664HBLJP-30	25 ns 30 ns	



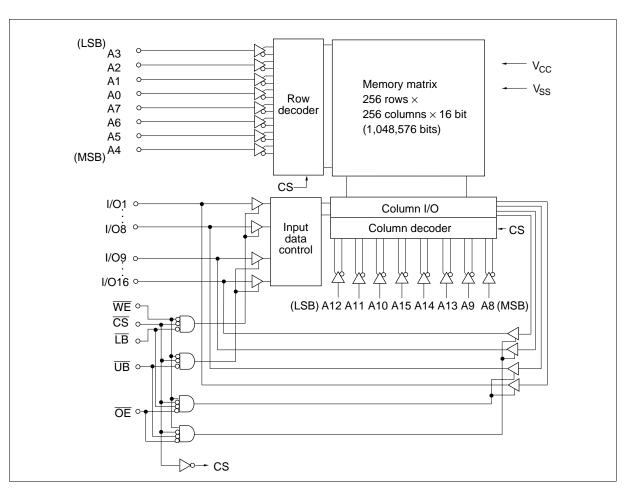
Pin Arrangement



Pin Description

Pin name	Function
A0 – A15	Address input
I/O1 – I/O16	Data input/output
CS	Chip select
ŌĒ	Output enable
WE	Write enable
UB	Upper byte select
LB	Lower byte select
V _{cc}	Power supply
V_{SS}	Ground
NC	No connection

Block Diagram



Function Table

CS	ΟE	WE	$\overline{\text{LB}}$	UB	Mode	V _{cc} current	I/O1-I/O8	I/O9-I/O16	Ref. cycle
Н	×	×	×	×	Standby	I_{SB}, I_{SB1}	High-Z	High-Z	_
L	Н	Н	×	×	Output disable	I _{cc}	High-Z	High-Z	_
L	L	Н	L	L	Read	I _{cc}	Output	Output	Read cycle
L	L	Н	L	Н	Lower byte read	I _{cc}	Output	High-Z	Read cycle
L	L	Н	Н	L	Upper byte read	I _{cc}	High-Z	Output	Read cycle
L	L	Н	Н	Н	_	I _{cc}	High-Z	High-Z	_
L	×	L	L	L	Write	I _{cc}	Input	Input	Write cycle
L	×	L	L	Н	Lower byte write	I _{cc}	Input	High-Z	Write cycle
L	×	L	Н	L	Upper byte write	I _{cc}	High-Z	Input	Write cycle
L	×	L	Н	Н	_	I _{cc}	High-Z	High-Z	_

Note: x: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Supply voltage relative to V _{SS}	V _{cc}	-0.5 to +4.6	V	
Voltage on any pin relative to V _{ss}	V _T	-0.5^{*1} to $V_{CC} + 0.5$	V	
Power dissipation	P _T	1.0	W	
Operating temperature	Topr	0 to +70	°C	
Storage temperature	Tstg	-55 to +125	°C	
Storage temperature under bias	Tbias	-10 to +85	°C	

Notes: 1. V_T (min) = -2.5 V for pulse width (under shoot) \leq 10 ns

Recommended DC Operating Conditions ($Ta = 0 \text{ to } +70^{\circ}\text{C}$)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{CC} *2	3.0	3.3	3.6	V
	V _{SS} *3	0	0	0	V
Input voltage	V _{IH}	2.0	_	V _{cc} + 0.3	V
	$\overline{V_{IL}}$	-0.3* ¹	_	0.8	V

Notes: 1. -2.0 V for pulse width (under shoot) $\leq 10 \text{ ns}$

- 2. The supply voltage with all $\rm V_{\rm cc}$ pins must be on the same level.
- 3. The supply voltage with all $V_{\rm ss}$ pins must be on the same level.

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 3.3 V \pm 0.3 V, V_{SS} = 0 V)

Parameter		Symbol	Min	Typ* ¹	Max	Unit	Test conditions
Input leakage current		I _{LI}	_	_	2	μΑ	$Vin = V_{SS}$ to V_{CC}
Output leakage current*1		I _{LO}	_	_	2	μΑ	$Vin = V_{ss} \text{ to } V_{cc}$
Operating power supply current	25 ns cycle	I _{cc}	_	_	100	mA	$\overline{\text{CS}} = \text{V}_{\text{IL}}, \text{ lout} = 0 \text{ mA}$ Other inputs = $\text{V}_{\text{IH}}/\text{V}_{\text{IL}}$
	30 ns cycle	I _{cc}	_	_	90	_	
Standby power supply current	25 ns cycle	I _{SB}	_	_	40	mA	CS = V _{IH} , Other inputs = V _{IH} /V _{IL}
	30 ns cycle	$I_{\rm SB}$	_	_	35		
		I _{SB1}	_	_	1	mA	$V_{CC} \ge \overline{CS} \ge V_{CC} - 0.2 \text{ V},$ (1) $0 \text{ V} \le \text{Vin} \le 0.2 \text{ V or}$ (2) $V_{CC} \ge \text{Vin} \ge V_{CC} - 0.2 \text{ V}$
			*2	*2	0.15*2	_	
Output voltage		V _{OL}	_	_	0.2	V	I _{OL} = 0.1 mA
			_	_	0.4	V	I _{OL} = 2 mA
		V _{OH}	V _{cc} - 0.2	_	_	V	I _{OH} = -0.1 mA
			2.4	_	_	V	I _{OH} = -2 mA

Note: 1. Typical values are at $V_{cc} = 3.3 \text{ V}$, $Ta = +25^{\circ}\text{C}$ and not guaranteed.

2. This characteristics is guaranteed only for L-version.

Capacitance (Ta = 25°C, f = 1.0 MHz)

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	_	6	pF	Vin = 0 V
Input/output capacitance*1	C _{I/O}	_	_	8	pF	V _{I/O} = 0 V

Note: 1. This parameter is sampled and not 100% tested.

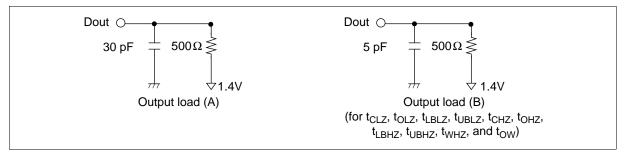
AC Characteristics (Ta = 0 to +70°C, V_{CC} = 3.3 V \pm 0.3 V, unless otherwise noted.)

Test Conditions

Input pulse levels: 2.4 V/0.4 V
Input rise and fall time: 3 ns

• Input and output timing reference levels: 1.4 V

• Output load: See figures (Including scope and jig)



Read Cycle

HM62W1664HB -25 HM62W1664HB -30

Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read cycle time	t _{RC}	25	_	30	_	ns	
Address access time	t _{AA}	_	25	_	30	ns	
Chip select access time	t _{ACS}	_	25	_	30	ns	
Output enable to output valid	t _{OE}	_	15	_	15	ns	
Byte select to output valid	t_{LB}, t_{UB}	_	15	_	15	ns	
Output hold from address change	t _{OH}	5	_	5	_	ns	
Chip select to output in low-Z	t _{CLZ}	5	_	5	_	ns	1
Output enable to output in low-Z	t _{OLZ}	1	_	1	_	ns	1
Byte select to output in low-Z	t_{LBLZ}, t_{UBLZ}	1	_	1	_	ns	1
Chip deselect to output in high-Z	t _{CHZ}	_	12	_	12	ns	1
Output disable to output in high-Z	t _{OHZ}	_	12	_	12	ns	1
Byte deselect to output in high-Z	t_{LBHZ}, t_{UBHZ}	_	12	_	12	ns	1

Write Cycle

HM62W1664HB -25 HM62W1664HB -30

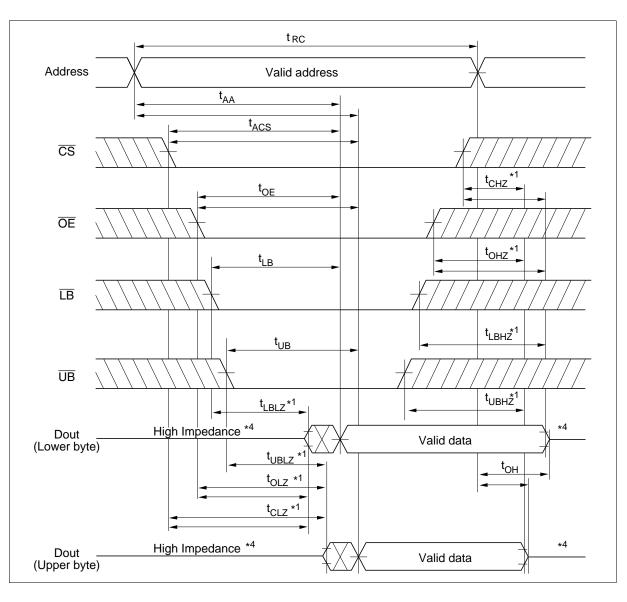
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{wc}	25	_	30	_	ns	
Address valid to end of write	t _{AW}	20	_	20	_	ns	
Chip select to end of write	t _{cw}	20	_	20	_	ns	8
Write pulse width	t _{wP}	20	_	20	_	ns	7
Byte select to end of write	t_{LBW}, t_{UBW}	20	_	20	_	ns	9, 10
Address setup time	t _{AS}	0	_	0	_	ns	5
Write recovery time	t _{wR}	0	_	0	_	ns	6
Data to write time overlap	t _{DW}	15	_	15	_	ns	
Data hold from write time	t _{DH}	0	_	0	_	ns	
Write disable to output in low-Z	t _{ow}	5	_	5	_	ns	1
Output disable to output in high-Z	t _{OHZ}	_	12	_	12	ns	1
Write enable to output in high-Z	t _{wHZ}	_	12	_	12	ns	1

Notes: 1. Transition is measured ±200 mV from steady voltage with Load (B). This parameter is sampled and not 100% tested.

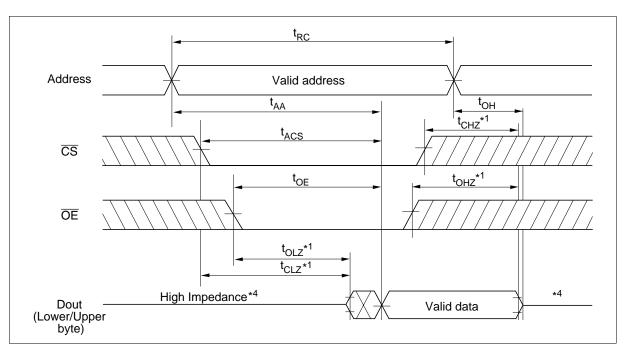
- 2. If the \overline{CS} or \overline{LB} or \overline{UB} low transition occurs simultaneously with the \overline{WE} low transition or after the \overline{WE} transition, output remains a high impedance state.
- 3. WE and/or CS must be high during address transition time.
- 4. If \overline{CS} , \overline{OE} , \overline{LB} and \overline{UB} are low during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
- 5. t_{AS} is measured from the latest address transition to the latest of \overline{CS} , \overline{WE} , \overline{LB} or \overline{UB} going low.
- 6. t_{we} is measured from the earliest of \overline{CS} , \overline{WE} , \overline{LB} or \overline{UB} going high to the first address transition.
- 7. A write occurs during the overlap of low \overline{CS} , low \overline{WE} and low \overline{LB} or low \overline{UB} .
- 8. t_{cw} is measured from the later of \overline{CS} going low to the end of write.
- 9. t_{IBW} is measured from the later of \overline{LB} going low to the end of write.
- 10. t_{UBW} is measured from the later of $\overline{\text{UB}}$ going low to the end of write.

Timing Waveforms

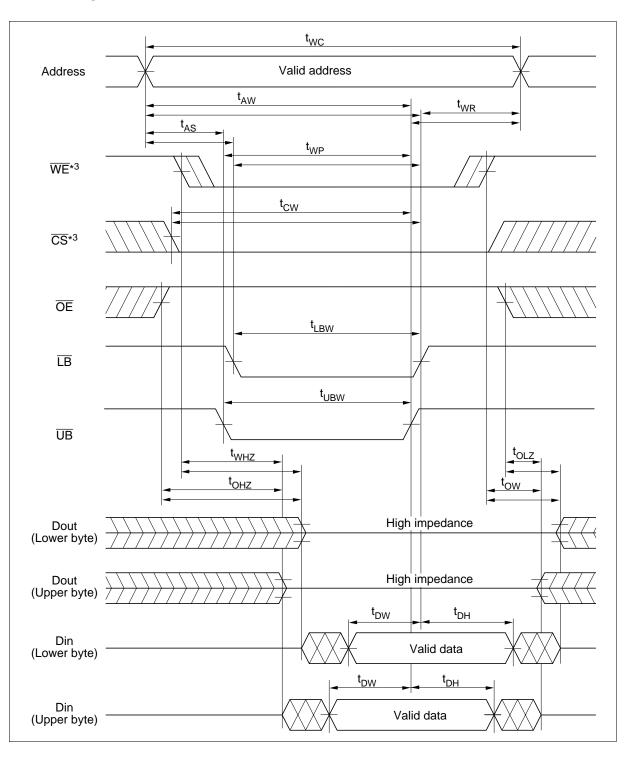
Read Timing Waveform (1) $(\overline{WE} = V_{IH})$



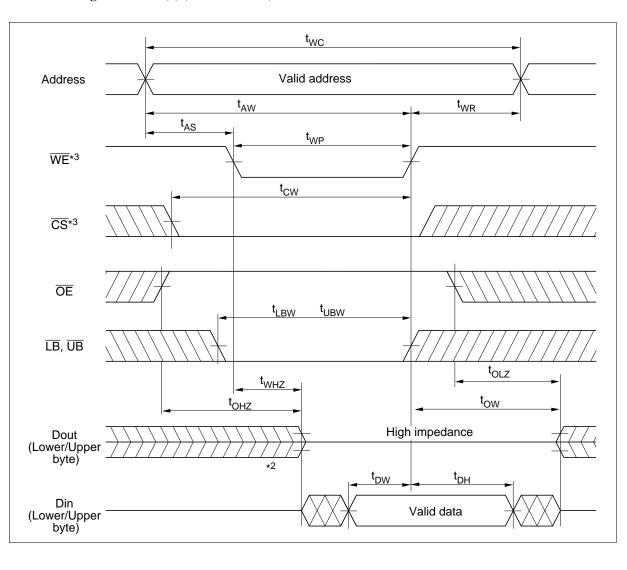
Read Timing Waveform (2) $(\overline{WE}=V_{IH},\overline{LB}=V_{IL},\overline{UB},=V_{IL})$



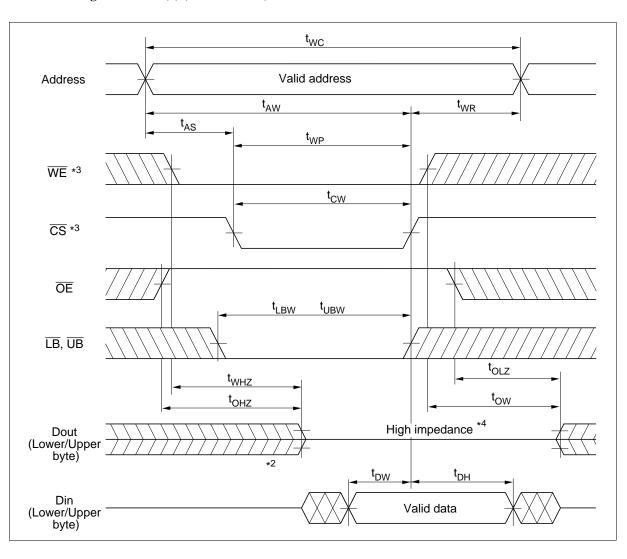
Write Timing Waveform (1) (\overline{LB} , \overline{UB} Controlled)



Write Timing Waveform (2) (WE Controlled)



Write Timing Waveform (3) ($\overline{\text{CS}}$ Controlled)



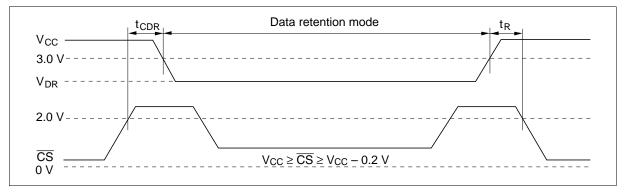
Low \mathbf{V}_{CC} Data Retention Characteristics (Ta = 0 to +70°C)

This characteristics is guaranteed only for L-version.

Parameter	Symbol	Min	Typ*1	Max	Unit	Test conditions
V _{cc} for data retention	V_{DR}	2.0	_	_	V	$V_{CC} \ge \overline{CS} \ge V_{CC} - 0.2 \text{ V},$ (1) $0 \text{ V} \le \text{Vin} \le 0.2 \text{ V or}$ (2) $V_{CC} \ge \text{Vin} \ge V_{CC} - 0.2 \text{ V}$
Data retention current	I _{CCDR}	_	2	80	μА	$V_{CC} = 3 \text{ V} V_{CC} \ge \overline{\text{CS}} \ge V_{CC} - 0.2 \text{ V}, (1) 0 \text{ V} \le \text{Vin} \le 0.2 \text{ V or} (2) V_{CC} \ge \text{Vin} \ge V_{CC} - 0.2 \text{ V}$
Chip deselect to data retention time	t _{CDR}	0	_	_	ns	See retention waveform
Operation recovery time	t _R	5	_	_	ms	

Note: 1. Typical values are at $V_{cc} = 3.0 \text{ V}$, $Ta = 25^{\circ}\text{C}$, and not guaranteed.

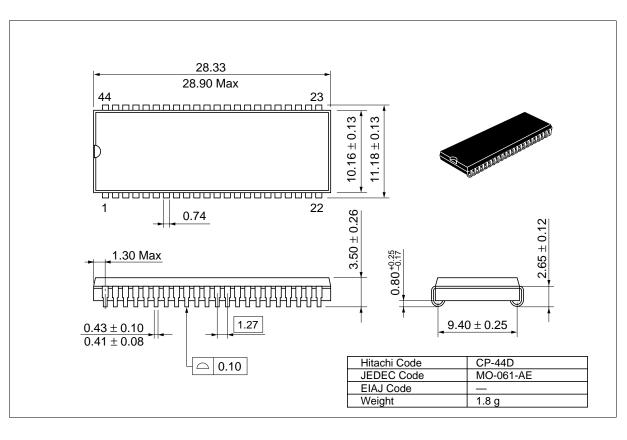
Low V_{CC} Data Retention Timing Waveform



Package Dimensions

HM62W1664HBJP/HBLJP Series (CP-44D)

Unit: mm



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HITACHI

Hitachi, Ltd.

Semiconductor & IC Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100, Japan Tel: Tokyo (03) 3270-2111

Fax: (03) 3270-5109

For further information write to:

Hitachi America, Ltd. Semiconductor & IC Div. 2000 Sierra Point Parkway Brisbane, CA. 94005-1835 U S A

Tel: 415-589-8300 Fax: 415-583-4207 Hitachi Europe GmbH Electronic Components Group Continental Europe Dornacher Straße 3 D-85622 Feldkirchen München Tel: 089-9 91 80-0

Fax: 089-9 29 30 00

Hitachi Europe Ltd.
Electronic Components Div.
Northern Europe Headquarters
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA
United Kingdom
Tel: 0628-585000
Fax: 0628-778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 0104 Tel: 535-2100 Fax: 535-1533

Hitachi Asia (Hong Kong) Ltd. Unit 706, North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon Hong Kong

Tel: 27359218 Fax: 27306071

Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Aug. 3, 1995	Initial issue	T. Nojiri	K. Yoshizaki
0.1	Jul. 18, 1996	Change of Block Diagram Function Table Addition of Mode Parameter Recommended DC Operating Conditions Change of note 2. Addition of note 3. DC Characteristics Addition of note 2 AC Characteristics Change order of notes t _{oe} (max): 12/15 ns to 15/15 ns t _{aw} (min): 15/20 ns to 20/20 ns t _{cw} (min): 15/20 ns to 20/20 ns t _{lbw} (min): 15/20 ns to 20/20 ns t _{lbw} , t _{ubw} (min): 15/20 ns to 20/20 ns t _{lbw} , (min): 15/20 ns to 15/15 ns t _{lbw} , (min): 12/15 ns to 15/15 ns t _{lbw} , (min): 12/15 ns to 15/15 ns t _{lbw} , (min): 12/15 ns to 15/15 ns t _{lbw} , (min): 10/10 ns to 12/12 ns Addition of t _{oe} (Write Cycle) Change of Timing Waveform Addition of Read Timing Waveform (2)	Y. Saito	A. Ide
1.0	Dec. 25, 1996	Deletion of Preliminary		